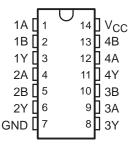
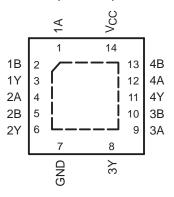
SCLS385J - SEPTEMBER 1997 - REVISED APRIL 2005

- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

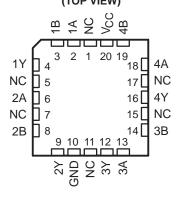
SN54LV32A . . . J OR W PACKAGE SN74LV32A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



SN74LV32A . . . RGY PACKAGE (TOP VIEW)



SN54LV32A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These quadruple 2-input positive-OR gates are designed for 2-V to 5.5-V V_{CC} operation.

The 'LV32A devices perform the Boolean function Y = A + B or $Y = \overline{A \cdot B}$ in positive logic.

ORDERING INFORMATION

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LV32ARGYR	LV32A
	0010 D	Tube of 50	SN74LV32AD	11/004
	SOIC - D	Reel of 2500	SN74LV32ADR	LV32A
	SOP - NS	Reel of 2000	SN74LV32ANSR	74LV32A
–40°C to 85°C	SSOP – DB	Reel of 2000	SN74LV32ADBR	LV32A
		Tube of 90	SN74LV32APW	
	TSSOP - PW	Reel of 2000	SN74LV32APWR	LV32A
		Reel of 250	SN74LV32APWT]
	TVSOP - DGV	Reel of 2000	SN74LV32ADGVR	LV32A
	CDIP – J	Tube of 25	SNJ54LV32AJ	SNJ54LV32AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV32AW	SNJ54LV32AW
	LCCC - FK	Tube of 55	SNJ54LV32AFK	SNJ54LV32AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SCLS385J - SEPTEMBER 1997 - REVISED APRIL 2005

description/ordering information (continued)

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Х	Н
Χ	Н	Н
L	L	L

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2)	
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	
Continuous current through V _{CC} or GND	
Package thermal impedance, θ _{JA} (see Note 3): D package	86°C/W
(see Note 3): DB package	96°C/W
(see Note 3): DGV package	127°C/W
(see Note 3): NS package	
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-5.



recommended operating conditions (see Note 5)

			SN54I	_V32A	SN74I	_V32A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
\/	High level input valte as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
VIH	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
V	_ow-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
VIL	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
٧ı	Input voltage		0	5.5	0	5.5	V
٧o	Output voltage		0 ,	Vcc	0	VCC	V
		V _{CC} = 2 V	S	-50		-50	μΑ
	High lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	90	-2		-2	
ЮН	High-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$	Q	-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12	
		$V_{CC} = 2 V$		50		50	μΑ
	Low lovel output output	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$		100		100	ns/V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN54	LV32A		SN7	4LV32A		
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			
.,	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			V
VOH	I _{OH} = -6 mA	3 V	2.48			2.48			V
	I _{OH} = -12 mA	4.5 V	3.8	N		3.8			
	I _{OL} = 50 μA	2 V to 5.5 V		N.	0.1			0.1	
.,	I _{OL} = 2 mA	2.3 V		Q.	0.4			0.4	V
V _{OL}	I _{OL} = 6 mA	3 V	ć		0.44			0.44	V
	I _{OL} = 12 mA	4.5 V	200		0.55			0.55	
lį	V _I = 5.5 V or GND	0 to 5.5 V	20,		±1			±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	Q.		20			20	μΑ
l _{off}	V_I or $V_O = 0$ to 5.5 V	0			5	·		5	μΑ
C	Vi – Vo a or CND	3.3 V		3.3		·	3.3		n.E
C _i	$V_I = V_{CC}$ or GND	5 V		3.3			3.3		pF



SCLS385J - SEPTEMBER 1997 - REVISED APRIL 2005

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

242445	FROM	то	LOAD	T,	ղ = 25°C	;	SN54LV32A	SN74L	.V32A	
PARAMETER	(INPUT) (OUTPU		UTPUT) CAPACITANCE		TYP	MAX	MIN MAX	MIN	MAX	UNIT
tool	A or B	V	C _L = 15 pF		7.1*	12.8*	O* 16*	1	15	20
^t pd	AUIB	Ť	C _L = 50 pF		9.6	16.2	1 20	1	19	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	DADAMETER	FROM	то	LOAD	T	ղ = 25°C	;	SN54LV32A	SN74L	V32A	
ı	PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
ı	t . Aor B	A or B	V	C _L = 15 pF		5*	7.9*	O 9.5*	1	9.5	20
ı	^t pd	AUIB	r	C _L = 50 pF		6.9	11.4	1 13	1	13	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T _A = 25°C		SN54LV32A	SN74LV32A		LINUT		
PARAMETER	(INPUT)	(OUTPUT)	PUT) CAPACITANCE		TYP	MAX	MIN MAX	MIN	MAX	UNIT	
+ .	A or B	V	C _L = 15 pF		3.6*	5.5*	0* 6.5*	1	6.5		
^t pd	AUB	r	C _L = 50 pF		4.9	7.5	8.5	1	8.5	ns	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 6)

	PARAMETER				
					UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V
V _{OL} (V)	Quiet output, minimum dynamic VOL		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3.1		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

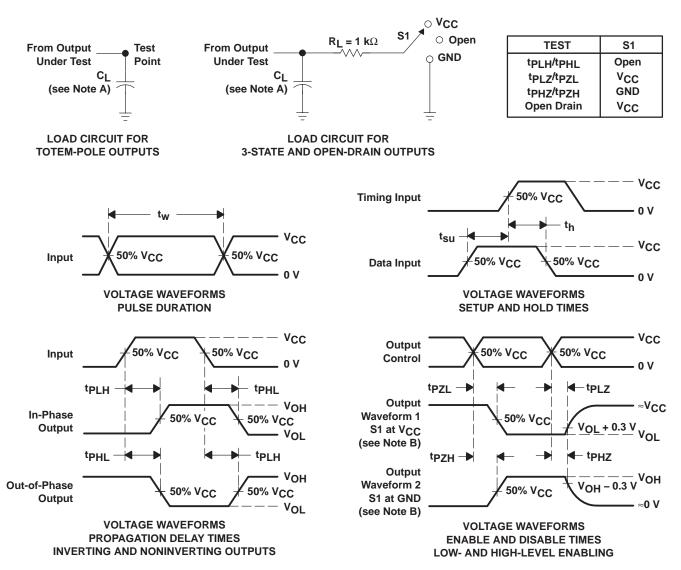
NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

	PARAMETER	TEST CO	VCC	TYP	UNIT	
<u> </u>	Dower discination conscitones	C. 50 pF	f 40 MH-	3.3 V	9.5	~F
Cbq	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	5 V	11.5	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV32AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LV32ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LV32APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV32ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

9-Aug-2005

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

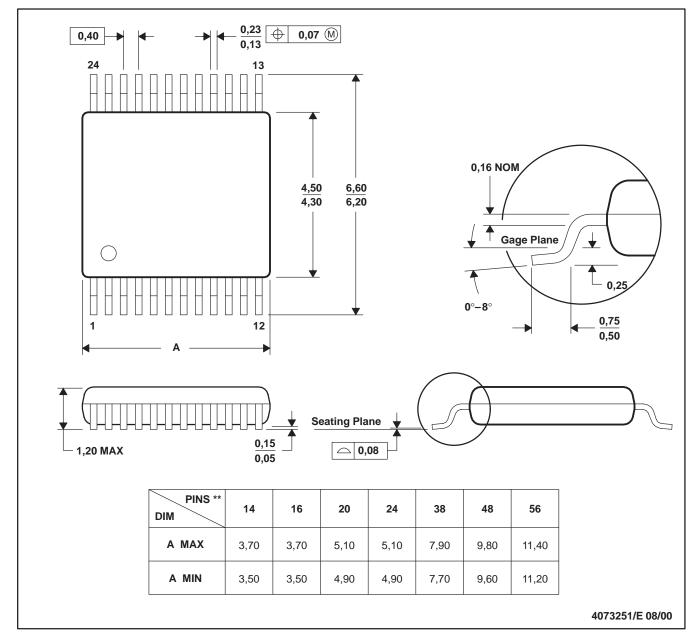
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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

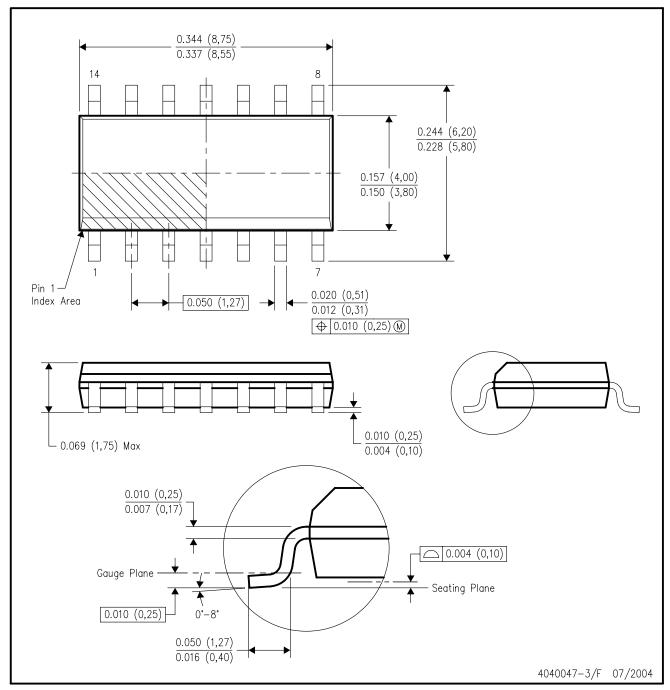
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



D (R-PDSO-G14)

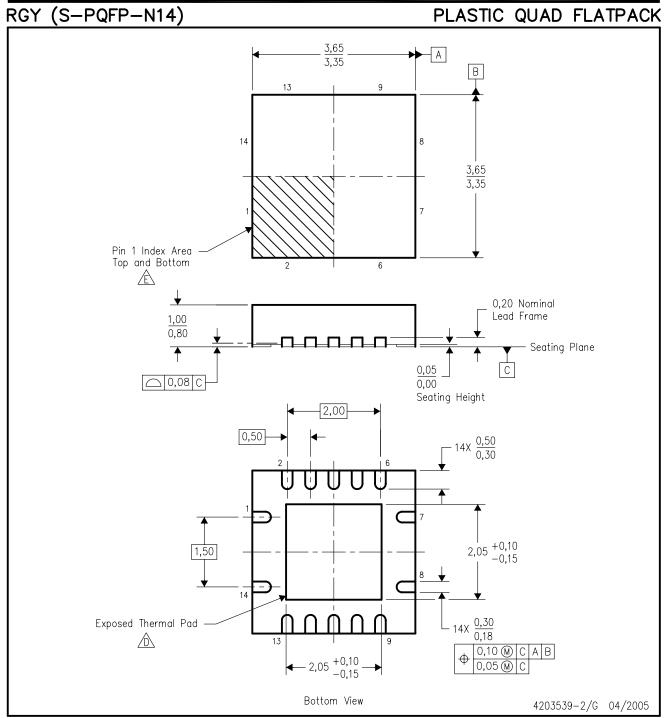
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.

Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

F. Package complies to JEDEC MO-241 variation BA.

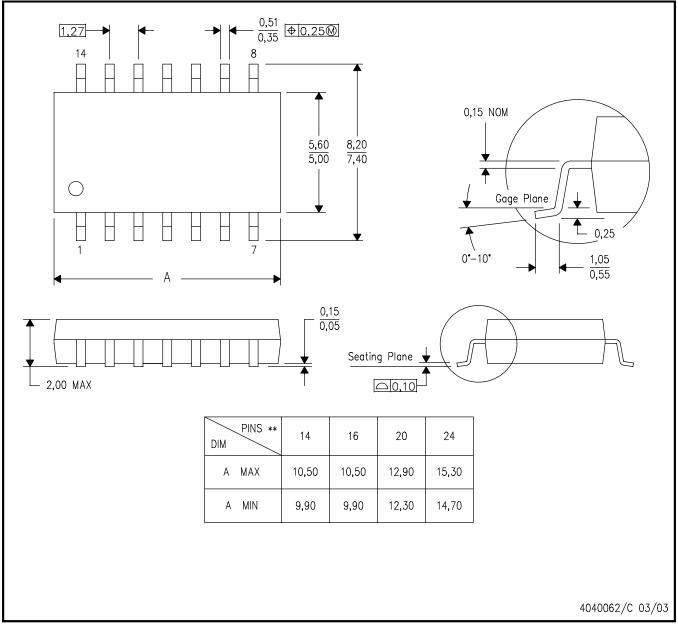


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

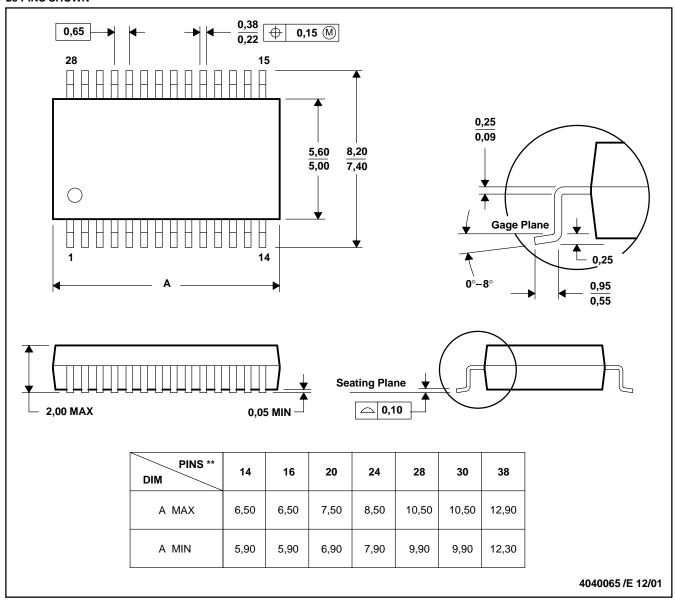
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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